

## Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
-30V	10mΩ@-20V	-12A
	12mΩ@-10V	
	15mΩ@-6V	
	20mΩ@-4.5V	

## Feature

- Trench Power LV MOSFET technology
- High density cell design for low  $R_{DS(ON)}$
- High Speed switching
- Suffix "-Q1" for AEC-Q101

## Application

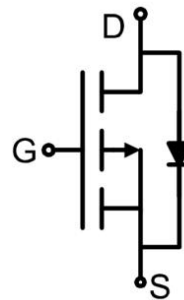
- Battery protection
- Load switch
- Power management

## Package



SOP-8

## Circuit diagram



## Marking



### Absolute maximum ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 25$	V
Continuous Drain Current	$I_D$	-12	A
Continuous Drain Current( $T_A=100^\circ\text{C}$ )	$I_{D(100^\circ\text{C})}$	-7.5	A
Pulsed Drain Current <sup>1)</sup>	$I_{DM}$	-100	A
Avalanche energy <sup>2)</sup>	$E_{AS}$	100	mJ
Power Dissipation <sup>3)</sup>	$P_D$	2.5	W
Thermal Resistance,Junction-to-Ambient <sup>4)</sup>	$R_{\theta JA}$	50	$^\circ\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 ~ +150	$^\circ\text{C}$

### Electrical characteristics ( $T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	-30			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=-30\text{V}, V_{GS}=0\text{V}$			-1	$\mu\text{A}$
Gate-body leakage current	$I_{GSS}$	$V_{GS}=\pm 25\text{V}, V_{DS}=0\text{V}$			$\pm 100$	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.2	-1.8	-2.8	V
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS}=-20\text{V}, I_D=-12\text{A}$		7.5	10	m $\Omega$
		$V_{GS}=-10\text{V}, I_D=-12\text{A}$		9	12	
		$V_{GS}=-6\text{V}, I_D=-10\text{A}$		11	15	
		$V_{GS}=-4.5\text{V}, I_D=-10\text{A}$		14.5	20	
<b>Dynamic characteristics<sup>5)</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS}=-15\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$		1860		pF
Output Capacitance	$C_{oss}$			310		
Reverse Transfer Capacitance	$C_{rss}$			280		
Total Gate Charge	$Q_g$	$V_{DS}=-15\text{V}, V_{GS}=-10\text{V}, I_D=-12\text{A}$		38		nC
Gate-Source Charge	$Q_{gs}$			5		
Gate-Drain Charge	$Q_{gd}$			10		
Turn-on delay time	$t_{d(on)}$	$V_{DD}=-15\text{V}, V_{GS}=-10\text{V}, I_D=-12\text{A}, R_{GEN}=2.3\Omega$		8		nS
Turn-on rise time	$t_r$			6		
Turn-off delay time	$t_{d(off)}$			95		
Turn-off fall time	$t_f$			62		
<b>Source-Drain Diode characteristics</b>						
Diode Forward Current	$I_S$				-12	A
Diode Forward voltage	$V_{SD}$	$V_{GS}=0\text{V}, I_S=-12\text{A}$			-1.2	V
Reverse Recovery Time	$t_{rr}$	$I_F=-12\text{A}, di/dt=100\text{A}/\mu\text{s}$		40		nS
Reverse Recovery Charge	$Q_{rr}$			19		nC

Notes:

- 1) Repetitive rating; pulse width limited by max. junction temperature.
- 2)  $T_J=25^\circ\text{C}, V_{DD}=-20\text{V}, V_G=-10\text{V}, R_G=25\Omega, L=0.5\text{mH}, I_{AS}=-20\text{A}$ .
- 3)  $P_d$  is based on max. junction temperature, using junction-case and junction-ambient thermal resistance.
- 4) The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in the still air environment with  $T_A=25^\circ\text{C}$ . The maximum allowed junction temperature of 150 $^\circ\text{C}$ . The value in any given application depends on the user's specific board design.
- 5) Guaranteed by design, not subject to production.

## Typical Characteristics

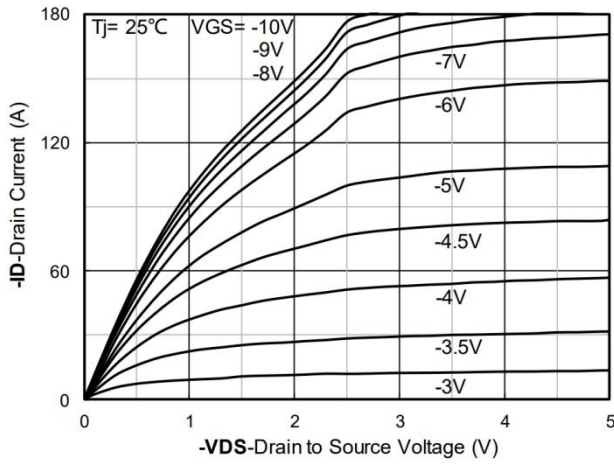


Figure 1. Output Characteristics

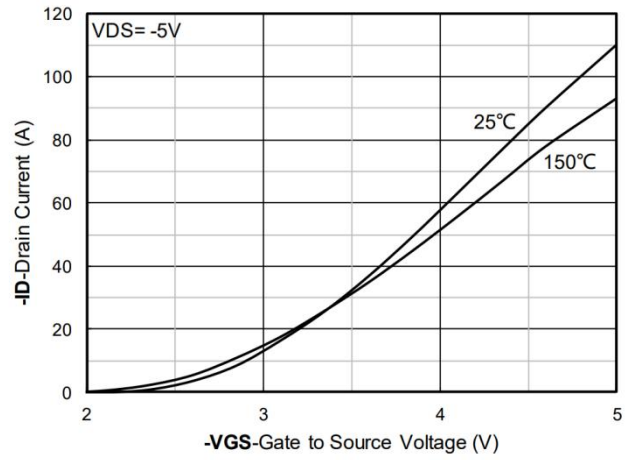


Figure 2. Transfer Characteristics

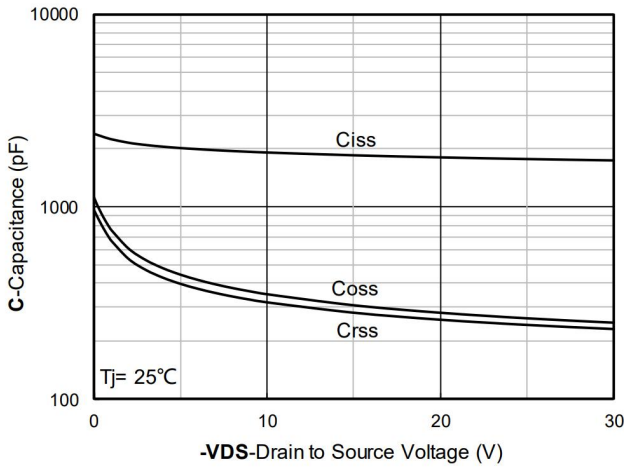


Figure 3. Capacitance Characteristics

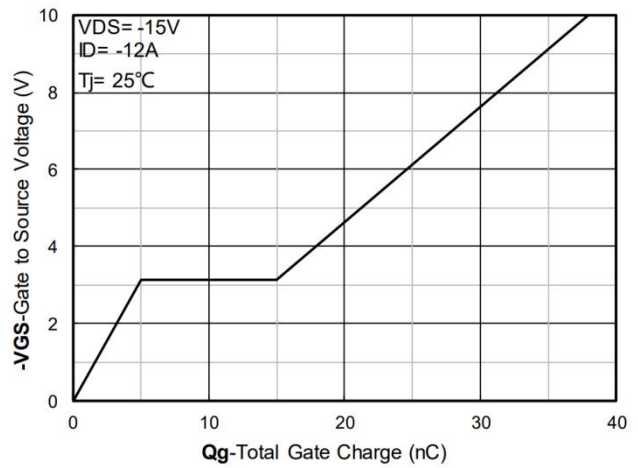


Figure 4. Gate Charge

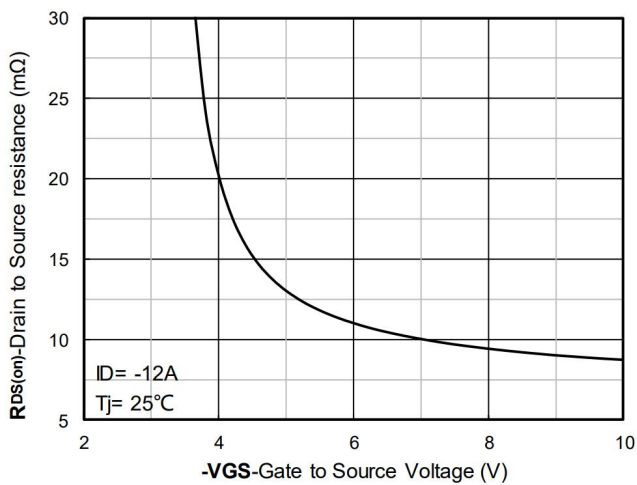


Figure 5. On-Resistance vs Gate to Source Voltage

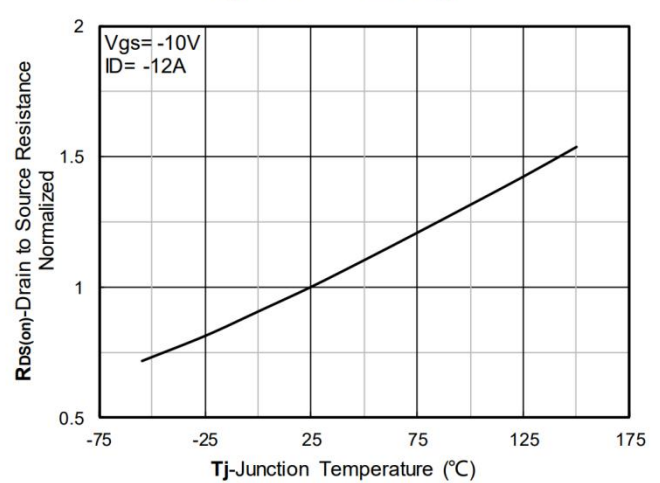


Figure 6. Normalized On-Resistance

## Typical Characteristics

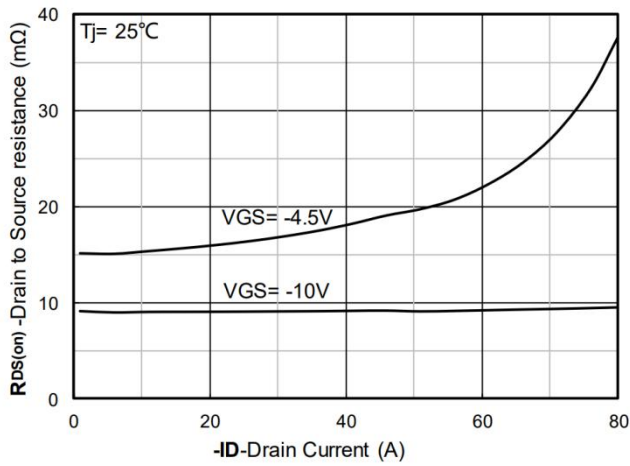


Figure 7. RDS(on) VS Drain Current

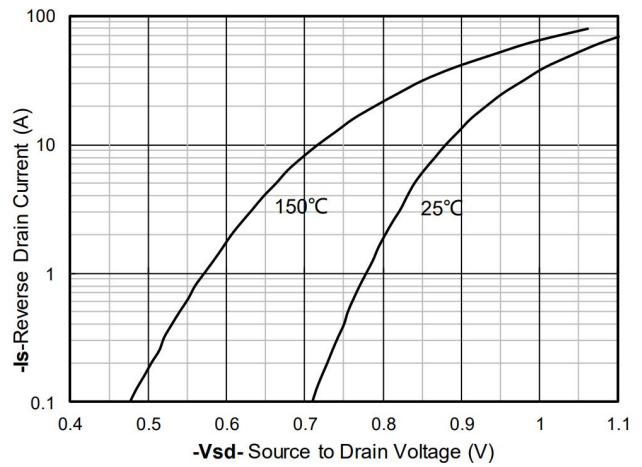


Figure 8. Forward characteristics of reverse diode

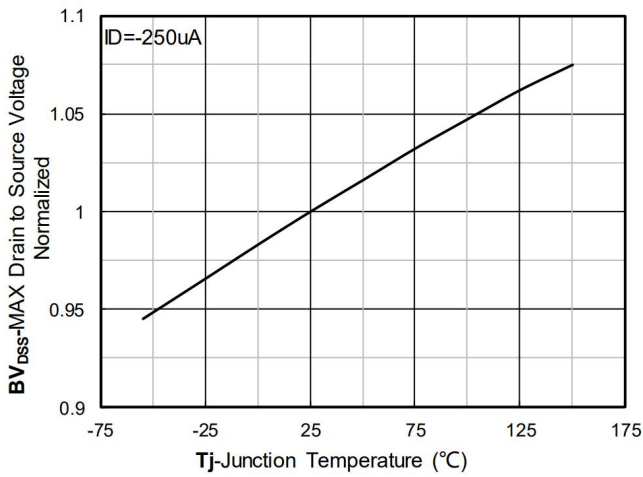


Figure 9. Normalized breakdown voltage

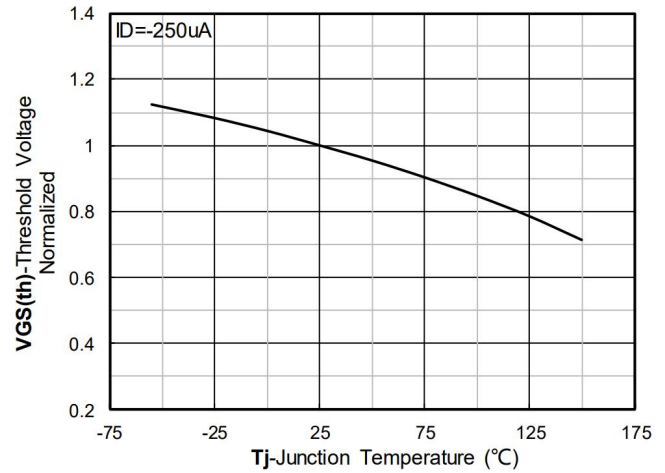


Figure 10. Normalized Threshold voltage

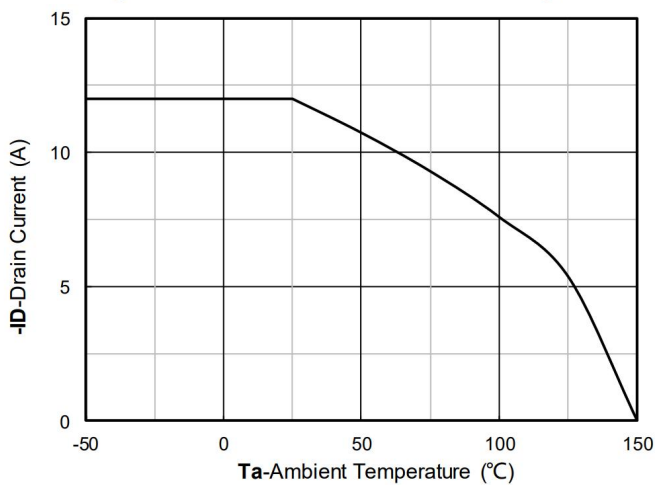


Figure 11. Current dissipation

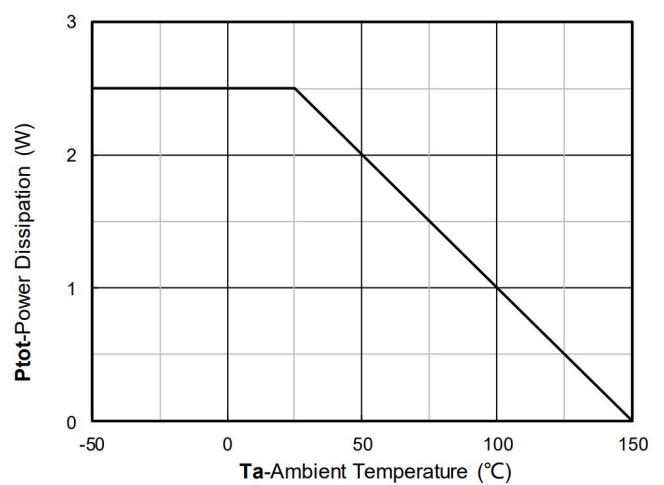


Figure 12. Power dissipation

## Typical Characteristics

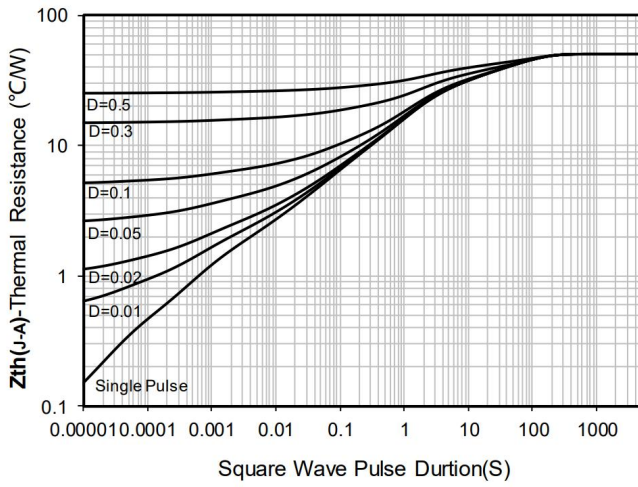


Figure 13. Maximum Transient Thermal Impedance

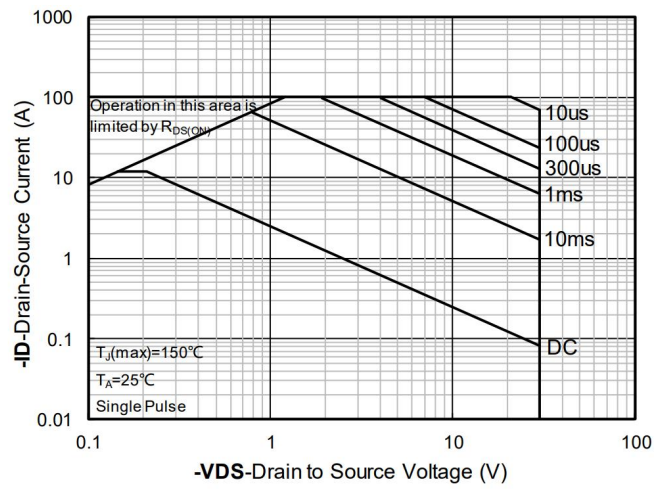
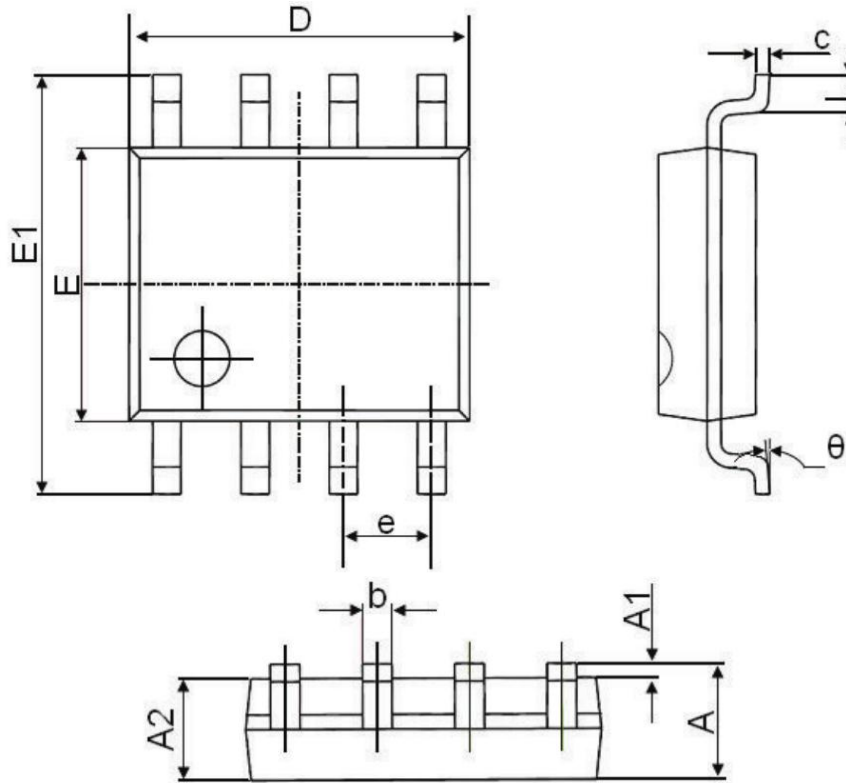


Figure 14. Safe Operation Area

## SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.250	1.650	0.049	0.065
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°